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Advanced Packaging Conference



R. Rettenmeier
Senior Product Marketing Manager
Evatec, Zurich, Switzerland



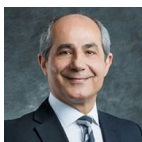
Biography

Roland Rettenmeier qualified as a Mechanical Engineer in 1997 and completed his MBA studies at Vienna, Austria in 2005. Roland extended his education through other international courses and programs since that time (e.g. Six Sigma Program with AT&S and Nokia; Innovation Technology Leader at Stanford University).

Roland has worked in the field of Electronics and Semiconductor manufacturing since 2001, managing multiple international projects. After joining Evatec in 2016 as Senior Product Marketing Manager (PMM) within the Business Unit for Advanced Packaging, he focused on business development for Panel Level Packaging where Evatec has now become the recognised market leader for thin film technology solutions. Since 2020 he has also supported development of Evatec's wafer level packaging solutions business.

In addition to his market and customer responsibilities, Roland represents Evatec in the Panel Level Packaging consortium of Fraunhofer IZM Berlin, in the Packaging Research Center at Georgia Tech, USA and in the Panel Level Packaging Consortium at the NCAP in Wuxi, China.

Welcome Remarks



L. Altimime
President
SEMI Europe, Berlin, Germany



Abstract

Coming Soon

Biography

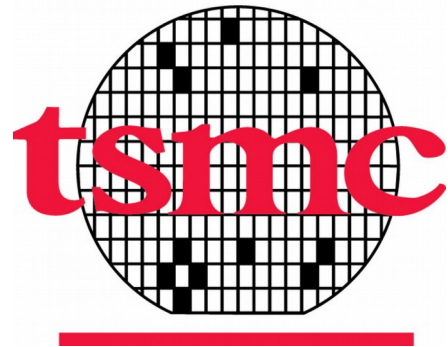
Laith Altimime, as President of SEMI Europe, leads SEMI's activities in Europe and the Middle East and

Africa (EMEA). Altimime has P&L responsibility as well as ownership of all Europe region programs and events, including SEMICON Europa. He is responsible for establishing industry standards, advocacy, community development, expositions, and programs. He provides support and services to SEMI members worldwide that have supply chain interests in Europe. He manages and nurtures relationships with SEMI members in the region and globally as well as with local associations and constituents in industry, government, and academia. Altimime has more than 30 years of international experience in the semiconductor industry. Prior to joining SEMI in 2015, He held senior leadership positions at NEC, KLA-Tencor, Infineon, Qimonda and imec. Altimime holds an MSc from Heriot-Watt University, Scotland.

Topic Coming Soon



D. Yu
Vice President of Pathfinding for System
Integration
TSMC, Taipei City, Taiwan



Abstract

Coming Soon

Biography

Dr. Douglas Yu is Vice President of Pathfinding for System Integration at Taiwan Semiconductor Manufacturing Co. Ltd. (TSMC). Prior to his appointment to Vice President in 2016, Dr. Yu was Senior Director of the Integrated Interconnect & Packaging Division.

Dr. Yu joined TSMC in 1994, serving in a variety of roles throughout his career including backend R&D, and developed technologies critical to the Company's highly successful transition to copper process at the 0.13 micron generation. Dr. Yu also pioneered TSMC's wafer-level system integration technologies, including Chip on Wafer on Substrate (CoWoS®), Integrated Fan-Out (InFO), and TSMC System on Integrated Chips (SoIC™), as well as their derivatives.

Prior to joining TSMC, Dr. Yu was a Member of Technical Staff and Project Leader at AT&T Bell Labs in USA, working on sub-micron process, device and integration technologies R&D from 1987 to 1994.

Dr. Yu became a Fellow of the Institute of Electrical and Electronics Engineers (IEEE) in 2013, and received the Presidential Science Prize of Taiwan in 2017 as well as the IEEE EPS Outstanding Manufacturing Technology Award in 2018. He has received more than 1,800 worldwide patents while serving at TSMC.

Dr. Yu received his B.S. degree in Physics and M.S. degree in Materials Science and Engineering both from National Tsing Hua University, and Ph.D. in Materials Engineering from Georgia Institute of Technology.

Latest Solutions in the Energy Efficiency of Electronic Systems



H. Voraberger
Corporate Vice President R&D
AT&S Austria Technologie & Systemtechnik
Aktiengesellschaft, Vienna, Austria



Abstract

Digitalization without further improvement in the energy efficiency of electronic systems will lead to a dramatic increase in energy requirements for data processing. The solution is based on processing systems with smaller nodes and a highly efficient power supply. Interconnect technology based on advanced IC substrate technologies offer great opportunities for improved signal processing and efficient power supply. Latest solutions will be presented in this talk.

Biography

Dr. Voraberger assumed his current position in 2010, as head of AT&S corporate research and development department. Previously Dr. Voraberger was responsible for AT&S corporate intellectual property and governmental funding.

He also established the R&D center in AT&S Shanghai (China) and was project leader for AT&S research and development in AT&S Leoben (Austria).

Dr. Voraberger studied industrial chemistry at Graz University of Technology, awarded multiple patents and has published several papers.